

9. ELECTRICAL DATA

9.1 INTRODUCTION

The following sections describe recommended electrical connections for the Intel386 DX, and its electrical specifications.

9.2 POWER AND GROUNDING

9.2.1 Power Connections

The Intel386 DX is implemented in CHMOS III and CHMOS IV technology and has modest power requirements. However, its high clock frequency and 72 output buffers (address, data, control, and HLDA) can cause power surges as multiple output buffers drive new signal levels simultaneously. For clean on-chip power distribution at high frequency, 20 V_{CC} and 21 V_{SS} pins separately feed functional units of the Intel386 DX.

Power and ground connections must be made to all external V_{CC} and GND pins of the Intel386 DX. On the circuit board, all V_{CC} pins must be connected on a V_{CC} plane. All V_{SS} pins must be likewise connected on a GND plane.

9.2.2 Power Decoupling Recommendations

Liberal decoupling capacitance should be placed near the Intel386 DX. The Intel386 DX driving its 32-bit parallel address and data buses at high frequencies can cause transient power surges, particularly when driving large capacitive loads.

Low inductance capacitors and interconnects are recommended for best high frequency electrical performance. Inductance can be reduced by shortening circuit board traces between the Intel386 DX and

decoupling capacitors as much as possible. Capacitors specifically for PGA packages are also commercially available, for the lowest possible inductance.

9.2.3 Resistor Recommendations

The ERROR# and BUSY# inputs have resistor pullups of approximately 20 K Ω built-in to the Intel386 DX to keep these signals negated when no Intel387 DX coprocessor is present in the system (or temporarily removed from its socket). The BS16# input also has an internal pullup resistor of approximately 20 K Ω , and the PEREQ input has an internal pull-down resistor of approximately 20 K Ω .

In typical designs, the external pullup resistors shown in Table 9-1 are recommended. However, a particular design may have reason to adjust the resistor values recommended here, or alter the use of pullup resistors in other ways.

9.2.4 Other Connection Recommendations

For reliable operation, always connect unused inputs to an appropriate signal level. N.C. pins should always remain unconnected.

Particularly when not using interrupts or bus hold, (as when first prototyping, perhaps) prevent any chance of spurious activity by connecting these associated inputs to GND:

Pin	Signal
B7	INTR
B8	NMI
D14	HOLD

If not using address pipelining, pullup D13 NA# to V_{CC} .

If not using 16-bit bus size, pullup C14 BS16# to V_{CC} .

Pullups in the range of 20 K Ω are recommended.

Table 9-1. Recommended Resistor Pullups to V_{CC}

Pin and Signal	Pullup Value	Purpose
E14 ADS#	20 K Ω \pm 10%	Lightly Pull ADS# Negated During Intel386 DX Hold Acknowledge States
C10 LOCK#	20 K Ω \pm 10%	Lightly Pull LOCK# Negated During Intel386 DX Hold Acknowledge States

9.3 MAXIMUM RATINGS

Table 9-2. Maximum Ratings

Parameter	Intel386™ DX 20, 25, 33 MHz Maximum Rating
Storage Temperature	-65°C to +150°C
Case Temperature Under Bias	-65°C to +110°C
Supply Voltage with Respect to V _{SS}	-0.5V to +6.5V
Voltage on Other Pins	-0.5V to V _{CC} + 0.5V

Table 9-2 is a stress rating only, and functional operation at the maximums is not guaranteed. Functional operating conditions are given in 9.4 D.C. Specifications and 9.5 A.C. Specifications.

Extended exposure to the Maximum Ratings may affect device reliability. Furthermore, although the Intel386 DX contains protective circuitry to resist damage from static electric discharge, always take precautions to avoid high static voltages or electric fields.

9.4 D.C. SPECIFICATIONS

Functional Operating Range: V_{CC} = 5V ± 5%; T_{CASE} = 0°C to 85°C

Table 9-3. Intel386™ DX D.C. Characteristics

Symbol	Parameter	Intel386™ DX 20 MHz, 25 MHz, 33 MHz		Unit	Test Conditions
		Min	Max		
V _{IL}	Input Low Voltage	-0.3	0.8	V	(Note 1)
V _{IH}	Input High Voltage	2.0	V _{CC} + 0.3	V	
V _{ILC}	CLK2 Input Low Voltage	-0.3	0.8	V	(Note 1)
V _{IHC}	CLK2 Input High Voltage 20 MHz 25 MHz and 33 MHz	V _{CC} - 0.8	V _{CC} + 0.3	V	
		3.7	V _{CC} + 0.3	V	
V _{OL}	Output Low Voltage I _{OL} = 4 mA: A2-A31, D0-D31 I _{OL} = 5 mA: BE0#-BE3#, W/R#, D/C#, M/IO#, LOCK#, ADS#, HLDA		0.45	V	
			0.45	V	
V _{OH}	Output High Voltage I _{OH} = 1 mA: A2-A31, D0-D31 I _{OH} = 0.9 mA: BE0#-BE3#, W/R#, D/C#, M/IO#, LOCK#, ADS#, HLDA	2.4		V	
		2.4		V	
I _{LI}	Input Leakage Current (For All Pins except BS16#, PEREQ, BUSY#, and ERROR#)		± 15	µA	0V ≤ V _{IN} ≤ V _{CC}
I _{IH}	Input Leakage Current (PEREQ Pin)		200	µA	V _{IH} = 2.4V (Note 2)
I _{IL}	Input Leakage Current (BS16#, BUSY#, and ERROR# Pins)		-400	µA	V _{IL} = 0.45 (Note 3)
I _{LO}	Output Leakage Current		± 15	µA	0.45V ≤ V _{OUT} ≤ V _{CC}
I _{CC}	Supply Current CLK2 = 40 MHz: with 20 MHz Intel386™ DX CLK2 = 50 MHz: with 25 MHz Intel386™ DX CLK2 = 66 MHz: with 33 MHz Intel386™ DX		260	mA	(Note 4) I _{CC} Typ. = 200 mA
			320	mA	I _{CC} Typ. = 240 mA
			390	mA	I _{CC} Typ. = 300 mA
C _{IN}	Input or I/O Capacitance		10	pF	F _C = 1 MHz
C _{OUT}	Output Capacitance		12	pF	F _C = 1 MHz
C _{CLK}	CLK2 Capacitance		20	pF	F _C = 1 MHz

NOTES:

- The min value, -0.3, is not 100% tested.
- PEREQ input has an internal pulldown resistor.
- BS16#, BUSY# and ERROR# inputs each have an internal pullup resistor.
- CHMOS IV Technology (CHMOS III Max I_{CC} at 20 MHz, 25 MHz = 500 mA, 550 mA).

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9.5 A.C. SPECIFICATIONS

9.5.1 A.C. Spec Definitions

The A.C. specifications, given in Tables 9-4, 9-5, and 9-6, consist of output delays, input setup requirements and input hold requirements. All A.C. specifications are relative to the CLK2 rising edge crossing the 2.0V level.

A.C. spec measurement is defined by Figure 9-1. Inputs must be driven to the voltage levels indicated by Figure 9-1 when A.C. specifications are measured. Intel386 DX output delays are specified with minimum and maximum limits, measured as shown. The minimum Intel386 DX delay times are hold times

provided to external circuitry, Intel386 DX input setup and hold times are specified as minimums, defining the smallest acceptable sampling window. Within the sampling window, a synchronous input signal must be stable for correct Intel386 DX operation.

Outputs NA#, W/R#, D/C#, M/IO#, LOCK#, BE0#-BE3#, A2-A31 and HLDA only change at the beginning of phase one. D0-D31 (write cycles) only change at the beginning of phase two. The READY#, HOLD, BUSY#, ERROR#, PEREQ and D0-D31 (read cycles) inputs are sampled at the beginning of phase one. The NA#, BS16#, INTR and NMI inputs are sampled at the beginning of phase two.

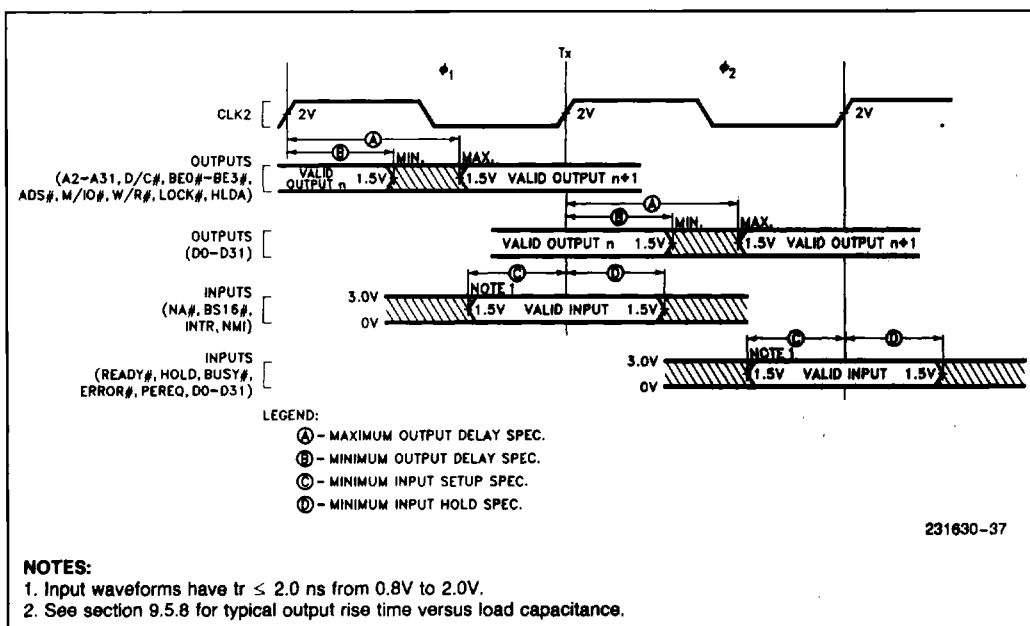


Figure 9-1. Drive Levels and Measurement Points for A.C. Specifications



9.5.2 A.C. Specification Tables

Functional Operating Range: $V_{CC} = 5V \pm 5\%$; $T_{CASE} = 0^{\circ}C$ to $+85^{\circ}C$

Table 9-4. 33 MHz Intel386™ DX A.C. Characteristics

Symbol	Parameter	33 MHz Intel386™ DX		Unit	Ref. Fig.	Notes
		Min	Max			
	Operating Frequency	8	33.3	MHz		Half of CLK2 Frequency
t1	CLK2 Period	15.0	62.5	ns	9-3	
t2a	CLK2 High Time	6.25		ns	9-3	at 2V
t2b	CLK2 High Time	4.5		ns	9-3	at 3.7V
t3a	CLK2 Low Time	6.25		ns	9-3	at 2V
t3b	CLK2 Low Time	4.5		ns	9-3	at 0.8V
t4	CLK2 Fall Time		4	ns	9-3	3.7V to 0.8V (Note 3)
t5	CLK2 Rise Time		4	ns	9-3	0.8V to 3.7V (Note 3)
t6	A2-A31 Valid Delay	4	15	ns	9-5	$C_L = 50$ pF
t7	A2-A31 Float Delay	4	20	ns	9-6	(Note 1)
t8	BE0#-BE3#, LOCK# Valid Delay	4	15	ns	9-5	$C_L = 50$ pF
t9	BE0#-BE3#, LOCK# Float Delay	4	20	ns	9-6	(Note 1)
t10	W/R#, M/IO#, D/C#, Valid Delay	4	15	ns	9-5	$C_L = 50$ pF
t10a	ADS# Valid Delay	4	14.5	ns	9-5	$C_L = 50$ pF
t11	W/R#, M/IO#, D/C#, ADS# Float Delay	4	20	ns	9-6	(Note 1)
t12	D0-D31 Write Data Valid Delay	7	24	ns	9-5a	$C_L = 50$ pF, (Note 4)
t12a	D0-D31 Write Data Hold Time	2			9-5b	$C_L = 50$ pF
t13	D0-D31 Float Delay	4	17	ns	9-6	(Note 1)
t14	HLDA Valid Delay	4	20	ns	9-6	$C_L = 50$ pF
t15	NA# Setup Time	5		ns	9-4	
t16	NA# Hold Time	2		ns	9-4	
t17	BS16# Setup Time	5		ns	9-4	
t18	BS16# Hold Time	2		ns	9-4	
t19	READY# Setup Time	7		ns	9-4	
t20	READY# Hold Time	4		ns	9-4	

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9.5.2 A.C. Specification Tables (Continued)Functional Operating Range: $V_{CC} = 5V \pm 5\%$; $T_{CASE} = 0^{\circ}C$ to $+85^{\circ}C$ **Table 9-4. 33 MHz Intel386™ DX A.C. Characteristics** (Continued)

Symbol	Parameter	33 MHz Intel386™ DX		Unit	Ref. Fig.	Notes
		Min	Max			
t21	D0–D31 Read Setup Time	5		ns	9-4	
t22	D0–D31 Read Hold Time	3		ns	9-4	
t23	HOLD Setup Time	11		ns	9-4	
t24	HOLD Hold Time	2		ns	9-4	
t25	RESET Setup Time	5		ns	9-7	
t26	RESET Hold Time	2		ns	9-7	
t27	NMI, INTR Setup Time	5		ns	9-4	(Note 2)
t28	NMI, INTR Hold Time	5		ns	9-4	(Note 2)
t29	PEREQ, ERROR#, BUSY# Setup Time	5		ns	9-4	(Note 2)
t30	PEREQ, ERROR#, BUSY# Hold Time	4		ns	9-4	(Note 2)

NOTES:

1. Float condition occurs when maximum output current becomes less than I_{LO} in magnitude. Float delay is not 100% tested.
2. These inputs are allowed to be asynchronous to CLK2. The setup and hold specifications are given for testing purposes, to assure recognition within a specific CLK2 period.
3. Rise and fall times are not tested.
4. Min. time not 100% tested.

9.5.2 A.C. Specification Tables (Continued)

 Functional Operating Range: $V_{CC} = 5V \pm 5\%$; $T_{CASE} = 0^{\circ}C$ to $+85^{\circ}C$
Table 9-5. 25 MHz Intel386™ DX A.C. Characteristics

Symbol	Parameter	25 MHz Intel386™ DX		Unit	Ref. Fig.	Notes
		Min	Max			
	Operating Frequency	4	25	MHz		Half of CLK2 Frequency
t1	CLK2 Period	20	125	ns	9-3	
t2a	CLK2 High Time	7		ns	9-3	at 2V
t2b	CLK2 High Time	4		ns	9-3	at 3.7V
t3a	CLK2 Low Time	7		ns	9-3	at 2V
t3b	CLK2 Low Time	5		ns	9-3	at 0.8V
t4	CLK2 Fall Time		7	ns	9-3	3.7V to 0.8V
t5	CLK2 Rise Time		7	ns	9-3	0.8V to 3.7V
t6	A2–A31 Valid Delay	4	21	ns	9-5	$C_L = 50$ pF
t7	A2–A31 Float Delay	4	30	ns	9-6	(Note 1)
t8	BE0#–BE3# Valid Delay	4	24	ns	9-5	$C_L = 50$ pF
t8a	LOCK# Valid Delay	4	21	ns	9-5	$C_L = 50$ pF
t9	BE0#–BE3#, LOCK# Float Delay	4	30	ns	9-6	(Note 1)
t10	W/R#, M/IO#, D/C#, ADS# Valid Delay	4	21	ns	9-5	$C_L = 50$ pF
t11	W/R#, M/IO#, D/C#, ADS# Float Delay	4	30	ns	9-6	(Note 1)
t12	D0–D31 Write Data Valid Delay	7	27	ns	9-5a	$C_L = 50$ pF
t12a	D0–D31 Write Data Hold Time	2			9-5b	$C_L = 50$ pF
t13	D0–D31 Float Delay	4	22	ns	9-6	(Note 1)
t14	HLDA Valid Delay	4	22	ns	9-6	$C_L = 50$ pF
t15	NA# Setup Time	7		ns	9-4	
t16	NA# Hold Time	3		ns	9-4	
t17	BS16# Setup Time	7		ns	9-4	
t18	BS16# Hold Time	3		ns	9-4	
t19	READY# Setup Time	9		ns	9-4	
t20	READY# Hold Time	4		ns	9-4	

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9.5.2 A.C. Specification Tables (Continued)Functional Operating Range: $V_{CC} = 5V \pm 5\%$; $T_{CASE} = 0^{\circ}C$ to $+85^{\circ}C$ **Table 9-5. 25 MHz Intel386™ DX A.C. Characteristics** (Continued)

Symbol	Parameter	25 MHz Intel386™ DX		Unit	Ref. Fig.	Notes
		Min	Max			
t21	D0–D31 Read Setup Time	7		ns	9-4	
t22	D0–D31 Read Hold Time	5		ns	9-4	
t23	HOLD Setup Time	15		ns	9-4	
t24	HOLD Hold Time	3		ns	9-4	
t25	RESET Setup Time	10		ns	9-7	
t26	RESET Hold Time	3		ns	9-7	
t27	NMI, INTR Setup Time	6		ns	9-4	(Note 2)
t28	NMI, INTR Hold Time	6		ns	9-4	(Note 2)
t29	PEREQ, ERROR #, BUSY # Setup Time	6		ns	9-4	(Note 2)
t30	PEREQ, ERROR #, BUSY # Hold Time	5		ns	9-4	(Notes 2, 3)

NOTES:

1. Float condition occurs when maximum output current becomes less than I_{LO} in magnitude. Float delay is not 100% tested.
2. These inputs are allowed to be asynchronous to CLK2. The setup and hold specifications are given for testing purposes, to assure recognition within a specific CLK2 period.

3.	Symbol	Parameter	Min
	$T_C = 0^{\circ}C$	t30 PEREQ, ERROR #, BUSY # Hold Time	4
	$T_C = +85^{\circ}C$	t30 PEREQ, ERROR #, BUSY # Hold Time	5

9.5.2 A.C. Specification Tables (Continued)

 Functional Operating Range: $V_{CC} = 5V \pm 5\%$; $T_{CASE} = 0^{\circ}C$ to $+85^{\circ}C$
Table 9.6. 20 MHz Intel386™ DX A.C. Characteristics

Symbol	Parameter	20 MHz Intel386™ DX		Unit	Ref. Fig.	Notes
		Min	Max			
	Operating Frequency	4	20	MHz		Half of CLK2 Frequency
t ₁	CLK2 Period	25	125	ns	9-3	
t _{2a}	CLK2 High Time	8		ns	9-3	at 2V
t _{2b}	CLK2 High Time	5		ns	9-3	at (V _{CC} - 0.8V)
t _{3a}	CLK2 Low Time	8		ns	9-3	at 2V
t _{3b}	CLK2 Low Time	6		ns	9-3	at 0.8V
t ₄	CLK2 Fall Time		8	ns	9-3	(V _{CC} - 0.8V) to 0.8V
t ₅	CLK2 Rise Time		8	ns	9-3	0.8V to (V _{CC} - 0.8V)
t ₆	A2-A31 Valid Delay	4	30	ns	9-5	C _L = 120 pF
t ₇	A2-A31 Float Delay	4	32	ns	9-6	(Note 1)
t ₈	BE0# - BE3#, LOCK# Valid Delay	4	30	ns	9-5	C _L = 75 pF
t ₉	BE0# - BE3#, LOCK# Float Delay	4	32	ns	9-6	(Note 1)
t ₁₀	W/R#, M/IO#, D/C#, ADS# Valid Delay	6	28	ns	9-5	C _L = 75 pF
t ₁₁	W/R#, M/IO#, D/C#, ADS# Float Delay	6	30	ns	9-6	(Note 1)
t ₁₂	D0-D31 Write Data Valid Delay	4	38	ns	9-5c	C _L = 120 pF
t ₁₃	D0-D31 Float Delay	4	27	ns	9-6	(Note 1)
t ₁₄	HLDA Valid Delay	6	28	ns	9-6	C _L = 75 pF
t ₁₅	NA# Setup Time	9		ns	9-4	
t ₁₆	NA# Hold Time	14		ns	9-4	
t ₁₇	BS16# Setup Time	13		ns	9-4	
t ₁₈	BS16# Hold Time	21		ns	9-4	
t ₁₉	READY# Setup Time	12		ns	9-4	
t ₂₀	READY# Hold Time	4		ns	9-4	
t ₂₁	D0-D31 Read Setup Time	11		ns	9-4	
t ₂₂	D0-D31 Read Hold Time	6		ns	9-4	
t ₂₃	HOLD Setup Time	17		ns	9-4	
t ₂₄	HOLD Hold Time	5		ns	9-4	
t ₂₅	RESET Setup Time	12		ns	9-7	

9.5.2 A.C. Specification Tables (Continued)Functional Operating Range: $V_{CC} = 5V \pm 5\%$; $T_{CASE} = 0^{\circ}C$ to $+85^{\circ}C$ **Table 9-6. 20 MHz Intel386™ DX A.C. Characteristics** (Continued)

Symbol	Parameter	20 MHz Intel386™ DX		Unit	Ref. Fig.	Notes
		Min	Max			
t ₂₆	RESET Hold Time	4		ns	9-7	
t ₂₇	NMI, INTR Setup Time	16		ns	9-4	(Note 2)
t ₂₈	NMI, INTR Hold Time	16		ns	9-4	(Note 2)
t ₂₉	PEREQ, ERROR #, BUSY # Setup Time	14		ns	9-4	(Note 2)
t ₃₀	PEREQ, ERROR #, BUSY # Hold Time	5		ns	9-4	(Note 2)

NOTES:

1. Float condition occurs when maximum output current becomes less than I_{LO} in magnitude. Float delay is not 100% tested.
2. These inputs are allowed to be asynchronous to CLK2. The setup and hold specifications are given for testing purposes, to assure recognition within a specific CLK2 period.

9.5.3 A.C. Test Loads

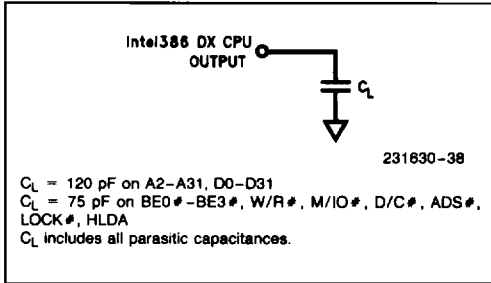


Figure 9-2. A.C. Test Load

9.5.4 A.C. Timing Waveforms

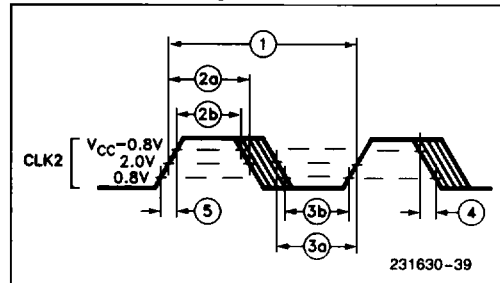


Figure 9-3. CLK2 Timing

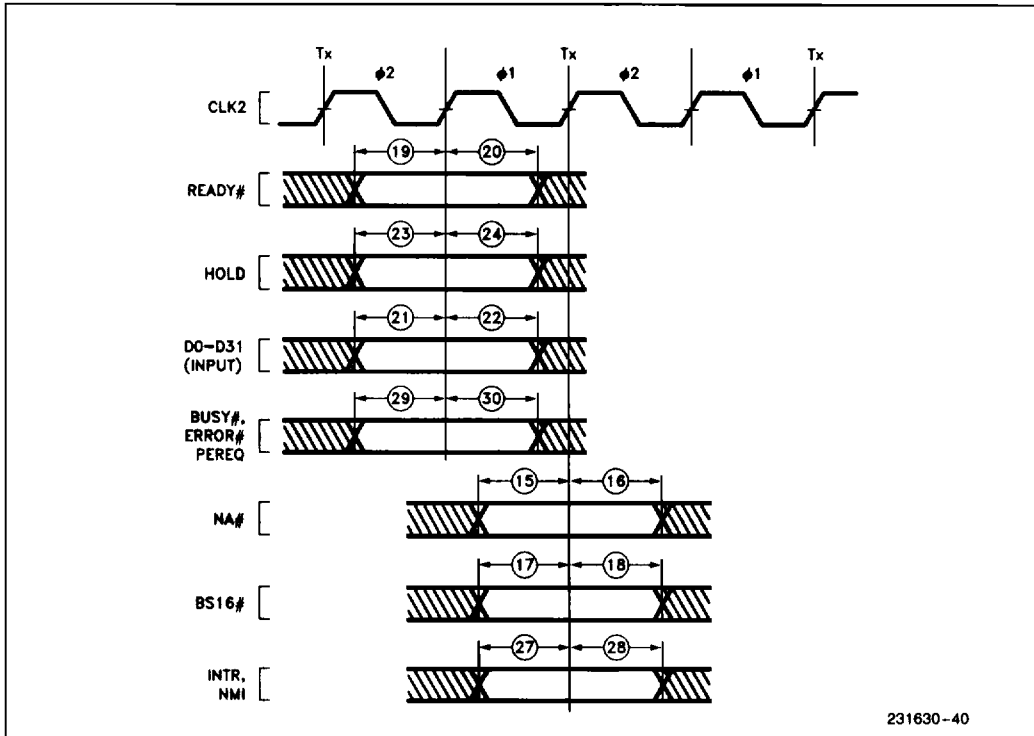


Figure 9-4. Input Setup and Hold Timing

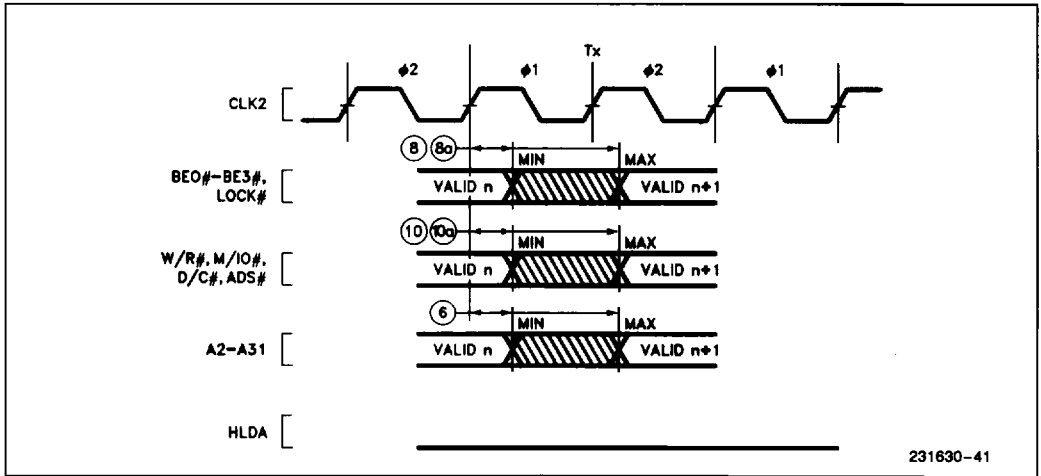


Figure 9-5. Output Valid Delay Timing

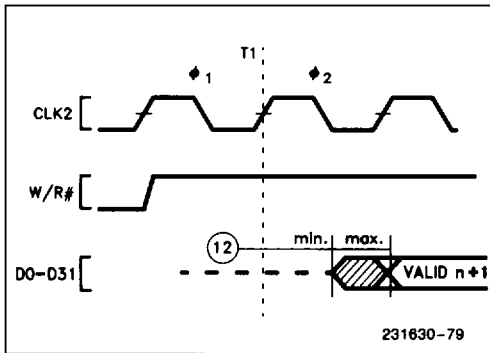


Figure 9-5a. Write Data Valid Delay Timing (25 MHz, 33 MHz)

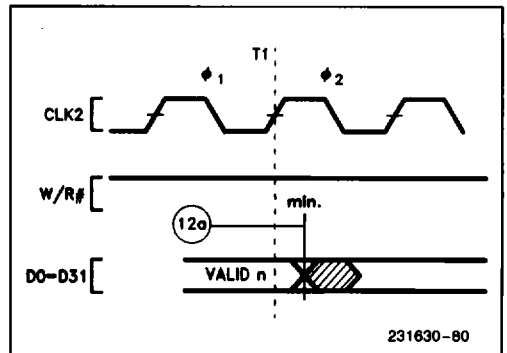


Figure 9-5b. Write Data Hold Timing (25 MHz, 33 MHz)

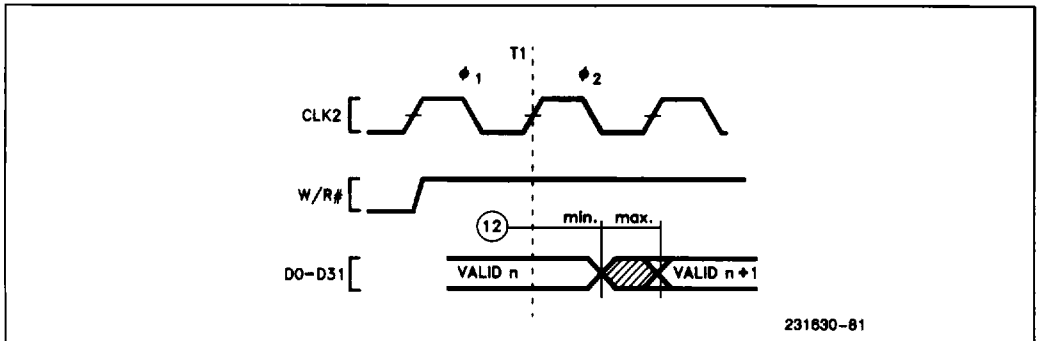
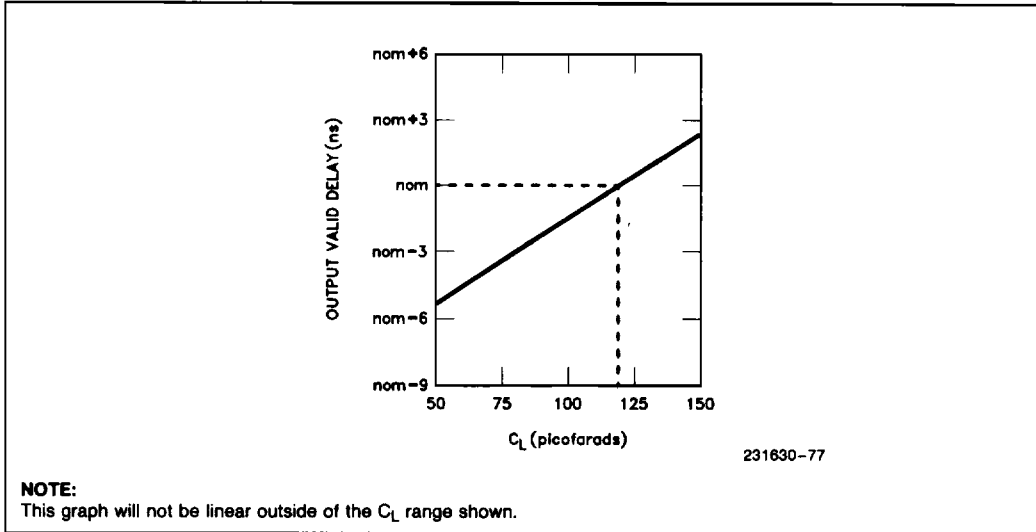


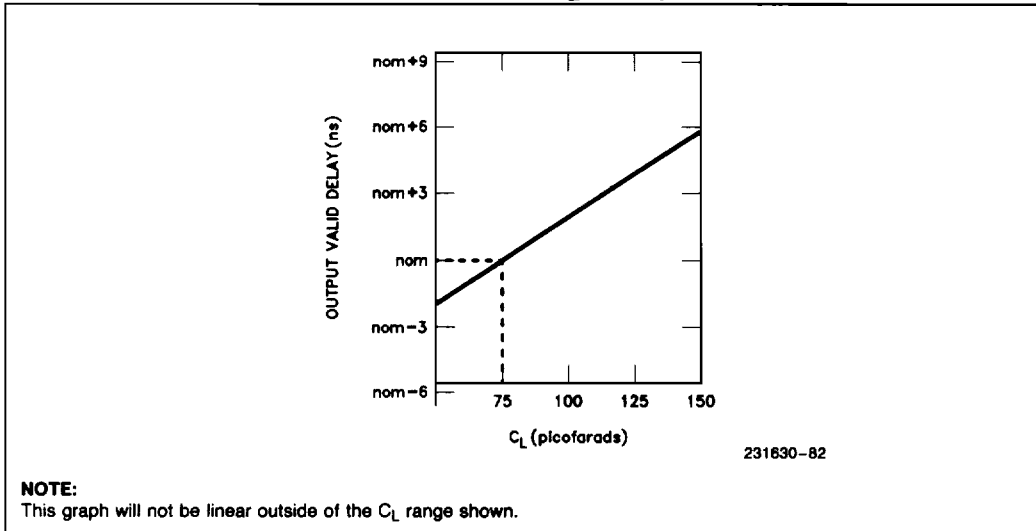
Figure 9-5c. Write Data Valid Delay Timing (20 MHz)

9.5.5 Typical Output Valid Delay Versus Load Capacitance at Maximum Operating Temperature ($C_L = 120$ pF)

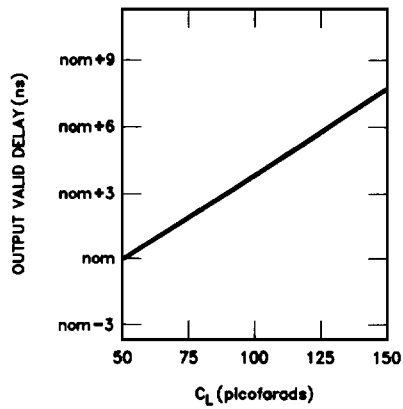


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9.5.6 Typical Output Valid Delay Versus Load Capacitance at Maximum Operating Temperature ($C_L = 75$ pF)



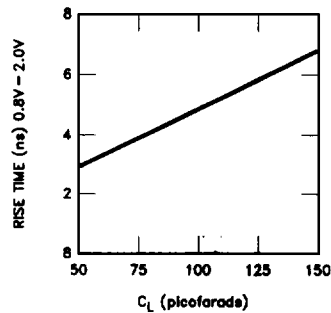
9.5.7 Typical Output Valid Delay Versus Load Capacitance at Maximum Operating Temperature ($C_L = 50$ pF)



231630-83

NOTE:This graph will not be linear outside of the C_L range shown.

9.5.8 Typical Output Rise Time Versus Load Capacitance at Maximum Operating Temperature



231630-78

NOTE:This graph will not be linear outside of the C_L range shown.

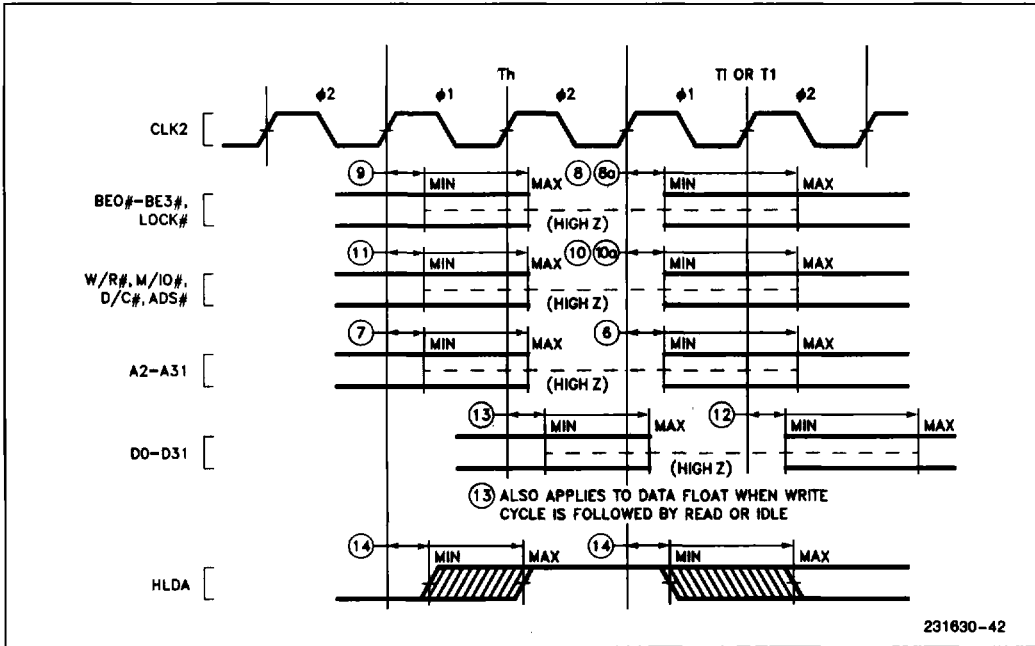


Figure 9-6. Output Float Delay and HLDA Valid Delay Timing

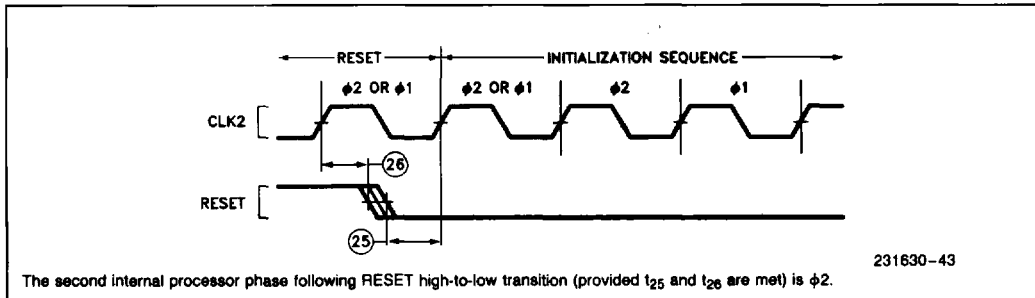


Figure 9-7. RESET Setup and Hold Timing, and Internal Phase

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